

### Features

- High current operation for greater luminous output
- Low power consumption and thermal resistance
- Can be used with automatic insertion equipment
- RoHS Compliant



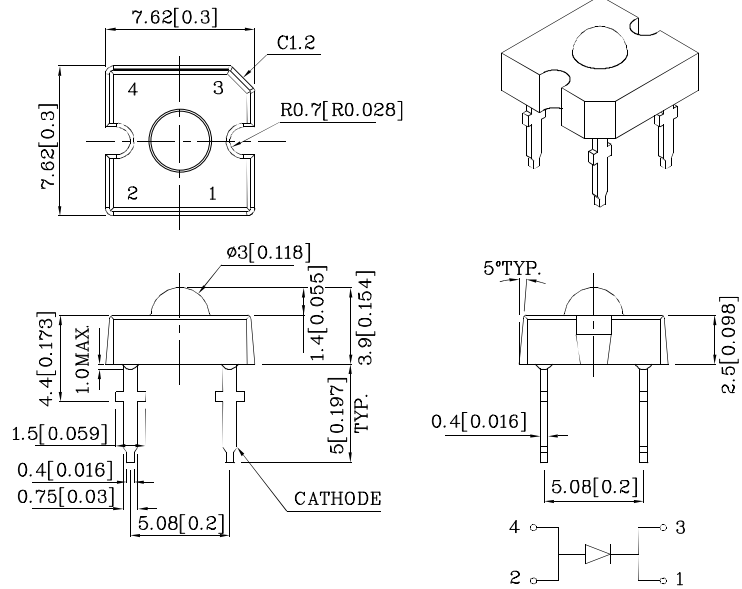
### Benefits:

- Rugged design allows for easy maintenance
- Robust package for optimum reliability

### Typical Applications:

- Automotive side markers
- Gaming and entertainment lighting
- Signs and road hazard indicators

### Package Schematics



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$ " unless otherwise noted.
3. Specifications are subject to change without notice.

| Absolute Maximum Ratings<br>( $T_A=25^\circ\text{C}$ )     |           | MO<br>(AlGaInP)     | Unit |
|--|-----------|---------------------|------|
| Reverse Voltage  | $V_R$     | 5                   | V    |
| DC Forward Current   | $I_F$     | 70                  | mA   |
| Power Dissipation  | $P_D$     | 189                 | mW   |
| Operating Temperature                                      | $T_A$     | -40 ~ +85           | °C   |
| Storage Temperature  | $T_{stg}$ | -55 ~ +85           |      |
| Lead Solder Temperature<br>[1.5mm Below Seating Plane.][1] |           | 260°C For 5 Seconds |      |

1.No Reflow soldering .

| Operating Characteristics<br>( $T_A=25^\circ\text{C}$ )                        |                    | MO<br>(AlGaInP) | Unit          |
|--|--------------------|-----------------|---------------|
| Forward Voltage (Typ.) ( $I_F=70\text{mA}$ )                                   | $V_F$              | 2.3             | V             |
| Forward Voltage (Max.) ( $I_F=70\text{mA}$ )                                   | $V_F$              | 2.7             | V             |
| Reverse Current (Max.) ( $V_R=5\text{V}$ )                                     | $I_R$              | 10              | $\mu\text{A}$ |
| Wavelength of Peak Emission<br>CIE127-2007*(Typ.)<br>( $I_F=70\text{mA}$ )     | $\lambda_P$        | 610*            | nm            |
| Wavelength of Dominant Emission<br>CIE127-2007*(Typ.)<br>( $I_F=70\text{mA}$ ) | $\lambda_D$        | 601*            | nm            |
| Spectral Line Full Width At Half<br>Maximum (Typ.) ( $I_F=70\text{mA}$ )       | $\Delta\lambda$    | 29              | nm            |
| Capacitance (Typ.) ( $V_F=0\text{V}$ , $f=1\text{MHz}$ )                       | C                  | 30              | pF            |
| Thermal Resistance (Typ.)  | $R_{\theta j-pin}$ | 125             | °C/W          |

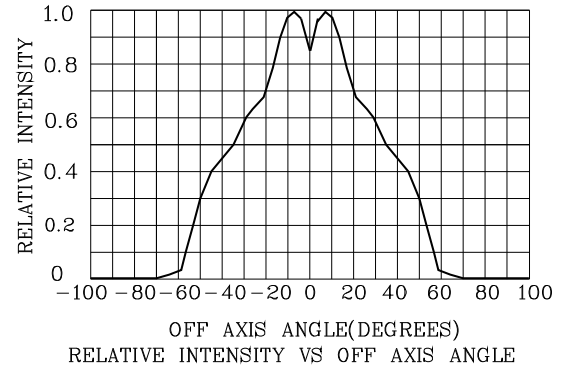
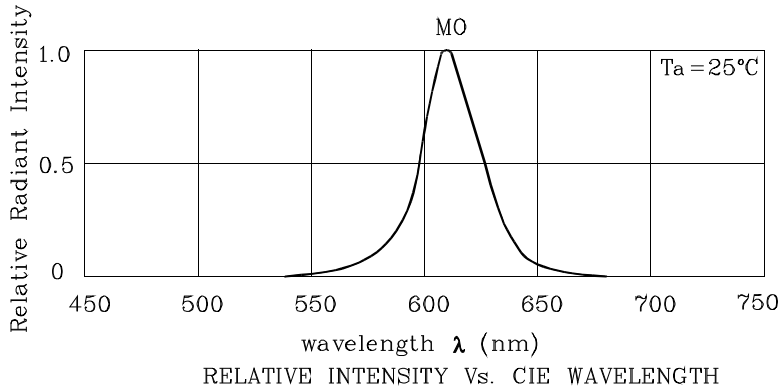
| Part Number | Emitting Color | Emitting Material | Lens-color  | Luminous Intensity<br>CIE127-2007*<br>( $I_F=70\text{mA}$ ) cd |              | Luminous Flux<br>CIE127-2007*<br>( $I_F=70\text{mA}$ ) lm | Wavelength<br>CIE127-2007*<br>$\lambda_P$ nm | Viewing Angle<br>2 $\theta$ 1/2 |
|-------------|----------------|-------------------|-------------|--|--------------|---|--|---------------------------------|
|             |                |                   |             | min.   | typ.         | typ.  |  |                                 |
| XSMO983W    | Orange         | AlGaInP           | Water Clear | 1.6<br>1*  | 2.79<br>1.6* | 2.8*  | 610*   | 70°                             |

1.Luminous intensity is measured with an integrating sphere after the device has stabilized.

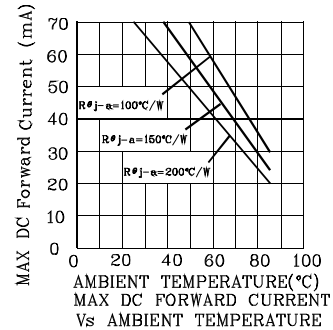
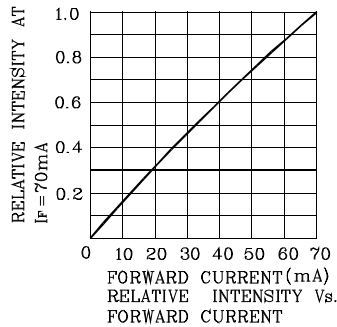
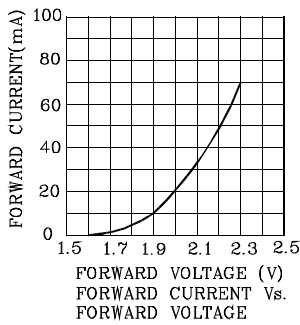
2. $\theta$  1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

3.LEDs are binned according to their Luminous intensity.

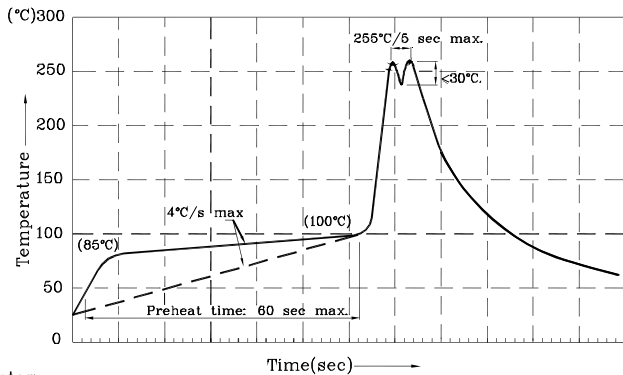
\* Luminous intensity / luminous flux value and wavelength are in accordance with CIE127-2007 standards.



❖ MO



Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:

- 1.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- 2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4.Fixtures should not incur stress on the component when mounting and during soldering process.
- 5.SAC 305 solder alloy is recommended.
- 6.No more than one wave soldering pass.

Remarks:

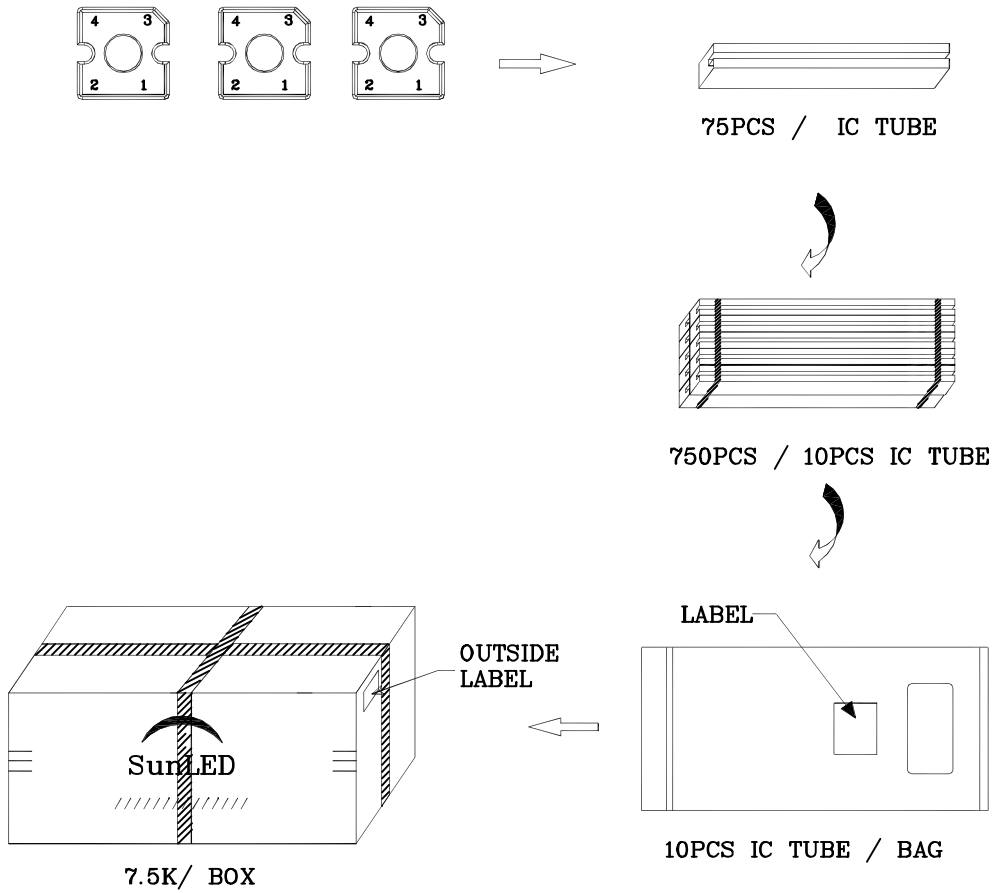
If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:


1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



**PACKING & LABEL SPECIFICATIONS**






Q.C. Q.C

XX XX XXXX

PASSED

|  |           |
|--|-----------|
| P/NO : XSxxx983x   |           |
| QTY : 750 pcs  | CODE: XXX |
| S/N : XX   |           |
| LOT NO:  |           |
| <br>XXXXXXXXXXXXXXXXXXXXXXXXXXXX |           |
| RoHS Compliant   |           |